conductive element forms [at least one] a contact pad extending beyond [a] the surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.

22. (Original) The method of claim 21, wherein the opening is a hole.

23. (Original) The method of claim 21, wherein the conductive element is a sphere.

24. (Original) The method of claim 21, wherein the conductive element is a cylinder.

27. (Currently Amended) A structure for interconnection between circuit layers, comprising:

a laminate having a conductive inner plane; and

a conductive element embedded into [a] the laminate wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element, and wherein the conductive element electrically connects the conductive inner plane to an outer surface of the laminate.

28. (Original) The structure of claim 27, further including an opening in the laminate that the conductive object is pressed into.

29. (Original) The structure of claim 28, wherein the opening is a hole in the laminate.

30. (Original) The structure of claim 27, wherein the conductive element is a sphere or a cylinder.

31. (Previously Amended) The structure of claim 27, wherein the outer element of the conductive element is a material selected from the group consisting of: glass, copper, brass, and bronze.

32. (Original) The structure of claim 27, wherein the laminate is selected from the group consisting of epoxy, cyanate-epoxy blend, and glass reinforced carrier.

33. (Original) The method of claim 21, wherein the inner element of the conductive element comprises a material selected from the group consisting of: glass, rubber and plastic.

34. (Original) The method of claim 21, wherein the outer element of the conductive element comprises a material selected from the group consisting of: copper, brass, gold and bronze.

35. (Original) The structure of claim 27, wherein the inner element of the conductive element comprises a material selected from the group consisting of: glass, rubber and plastic.

36. (Currently Amended) A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate; [and]

pressing a conductive element into the opening <u>such that a portion of at least one end of</u>

the conductive element extends beyond a surface of the laminate; and

applying a compressive pressure to at least one end of the conductive element, [wherein a portion of the] whereby the compressive pressure applied to the at least one end of the conductive element forms [at least one] a contact pad extending beyond a surface of the laminate.

37. (Currently Amended) A structure for interconnection between circuit layers, comprising:

a first laminate having a first conductive element embedded into [a] the first laminate wherein a portion of the first conductive element forms at least one contact pad extending beyond a surface of the first laminate;

a second laminate having a second conductive element embedded into the second laminate wherein a portion of the second conductive element forms at least one contact pad extending beyond a surface of the second laminate; and

a bonding layer between the first and second laminates, whereby the contact pads of the first and second conductive elements are electrically connected.

Please add the following new claims:

38. (New) A method of forming a conductive path within a laminate, comprising:

providing the laminate;

projecting a conductive element toward a surface of the laminate such that the conductive element moves toward the laminate, wherein the conductive element becomes embedded within the laminate.